

## News Release

### For Immediate Release

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## ITW EAE to Showcase Latest Semiconductor Packaging Equipment Developments at Semicon Taiwan

Lakeville, Minnesota, August 25, 2022 – ITW EAE will be showcasing its latest developments at Semicon Taiwan, September 14-16 at Taipei World Trade Center. The ITW EAE booth N0170 will have MPM, Camalot, Electrovert and Vitronics Soltec Applications Experts on hand as well as Sales and Management to answer questions and offer solutions.

**Camalot will be presenting live demonstrations of its Advanced Tilt and Rotate dispensing system.** This innovative and new Camalot design reduces wet out areas and improves capillary flow for underfill by accurately dispensing on the side walls of packages. State-of-the-art rotary actuators provide a fast, high precision, zero backlash mechanism that allows proprietary motion and controls allow articulation of the dispense pump in sub-degree increments for both axes as many times as you need, in other words total flexibility.

**MPM will be presenting live demonstrations of the Edison II ACT™ (Automatic Changeover Technology)** which is in the final stage of development. This innovative patent pending technology provides a simple, cost-effective solution that can be implemented in progressive stages towards full automation. It is designed to be easy to use and simple to adopt and requires no additional skills to operate. The solution utilizes the Edison printer and is designed to automate the changeover of solder paste cartridges, support tooling, squeegees, and stencils. The Edison is the most accurate printer in the market, with advanced technology needed for ultra-fine pitch and micro aperture printing processes.

ITW EAE plays a major role in semiconductor packaging, including stencil printing solder and flux, dispensing underfills and encapsulant liquids, thermal processing die attach adhesives, cleaning flux residue and remains, solder reflow and more. ITW EAE works with the world's leading semiconductor manufacturers in developing equipment that addresses evolving technical challenges while also meeting the need for higher throughput, yield, and performance.

*For more information visit [www.itweae.com](http://www.itweae.com).*